

YVi-LH / YVi-MH

- High-speed testing using 3-step dome lighting : 27msec/cm² (about 6 seconds for 150 x 150mm area, single lighting).
- Post-printing test : 2.5 D printing inspection using LASER (Metal squeegee printing).
Influence by foreign object, variation in soldering is observed. Connectable to QA option after printing.
- Post-mounting test : Variation in products and possible causes can be observed. Connectable to QA option after mounting.
- Post-reflow test : Inspection in Z direction using sharp angle LASER. Cut Post-reflow or Pre-reflow. Connectable to QA option Post-reflow.



● Sharp angle laser sensor

- Mounter, printer off-line linked : Multi functions such as quick conversion from the mounter data, NG marking, image storing, QA option and QA tracing.



YVi-LH

L size PCB applicable model

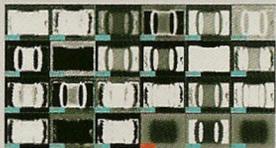
YVi-MH

M size PCB applicable model

Note : The photo shows the state with various options installed.

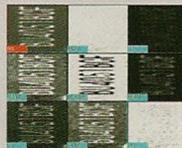
Visible rays

- General test to check presence/absence of components, bridge, deviation, etc.



Character recognition

- Robust character recognition function capable of reading even when grazed characters are mixed.



Infrared

- Test using penetrating near infrared without shining of flux.

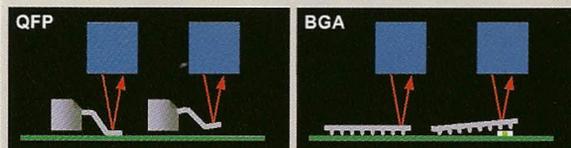


● Infrared

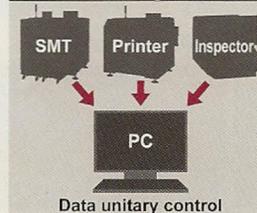
● Visible rays

LASER (=Z direction test)(Optional)

- Floating test of BGA, chip, lead.
- Testing engagement height of dip product as well.



Data unitary control



YVi-LH / YVi-MH specifications

	YVi-LH (Model : LE3-810)	YVi-MH (Model : LE3-310)
Applicable PCB	L460 x W410mm to L50 x W50mm	L330 x W250mm to L50 x W50mm
Test speed	27msec/cm ² (Equivalent to about 6 seconds for □150mm area) : Under single lighting, optimum condition	
Test resolution	LASER (XY direction) 1μm, LASER (Z direction) 10μm, Visible rays 19μm, Infrared 19μm	
Test item (Post-mounting)	Presence/absence of solder, excess, deviation, graze, dropping, blotting, bridge(standard), thickness of solder (LASER)	
Test item (Post-printing)	Position error, missing item, polarity, different item, angle deviation, standing, top/bottom, bent lead, bridge, character recognition(standard), floating chip, floating lead (LASER), foreign object (under YAMAHA condition)	
Test item (Post-reflow)	Position error, missing item, polarity, different item, angle deviation, standing, top/bottom, bent lead, bridge, character recognition(standard), floating chip, floating lead (LASER), foreign object, solder ball of component, fillet (under YAMAHA condition)	
Power supply	Single-phase AC200/208/220/230/240V +/-10% 50/60Hz	
Air supply source	0.4MPa or more, in clean, dry state.	
External dimension <Note 1>	L1,206 x W1,250 x H1,360mm (cover top)	L1,000 x W961 x H1,383mm (cover top)
Weight	Approx. 800kg	Approx. 480kg

<Note 1> This dimension does not include the projection.